



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

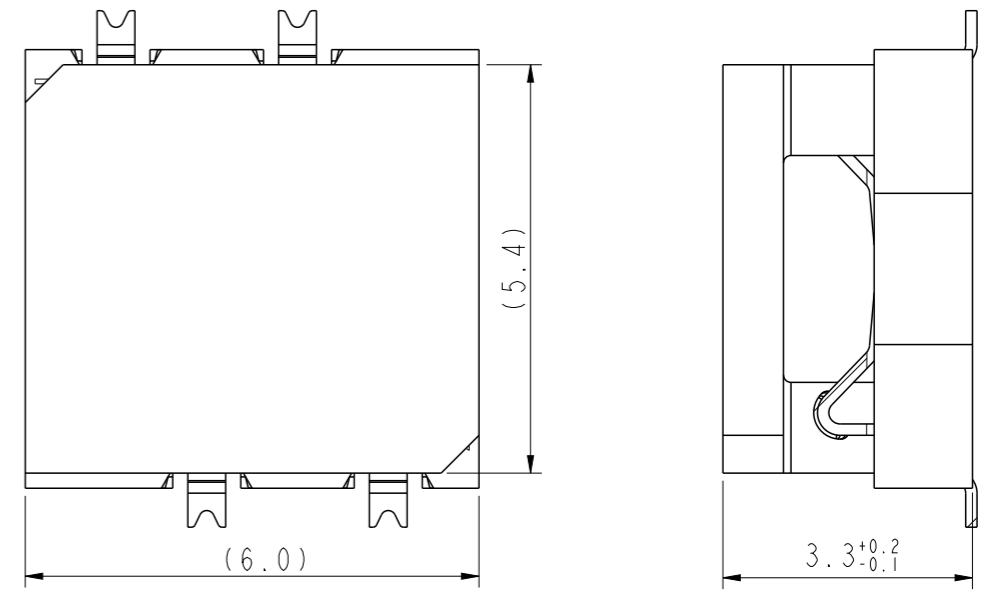
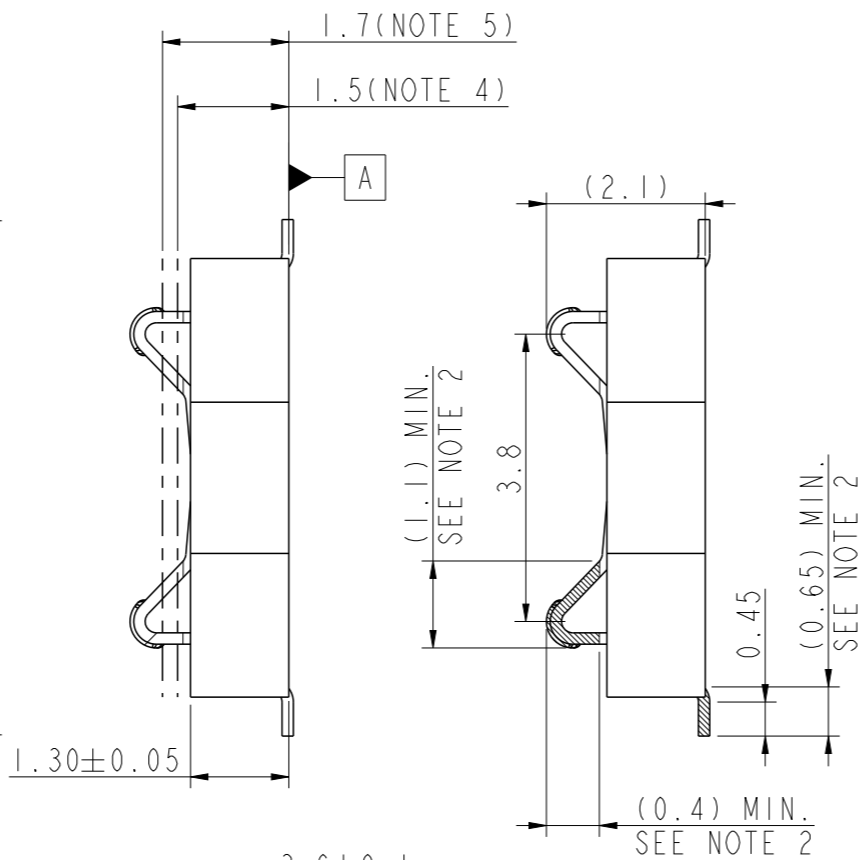
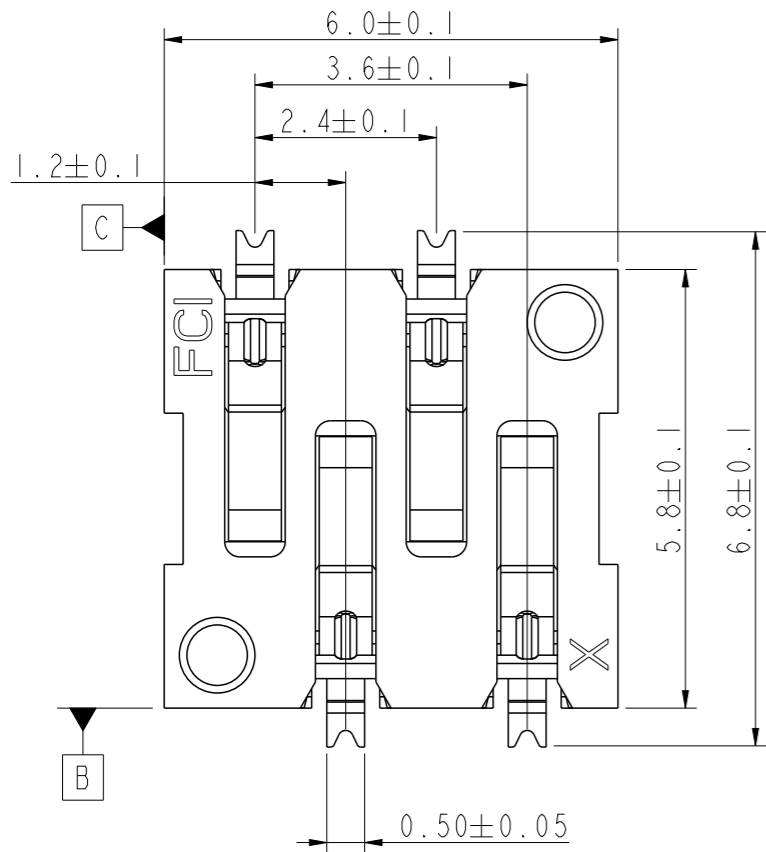
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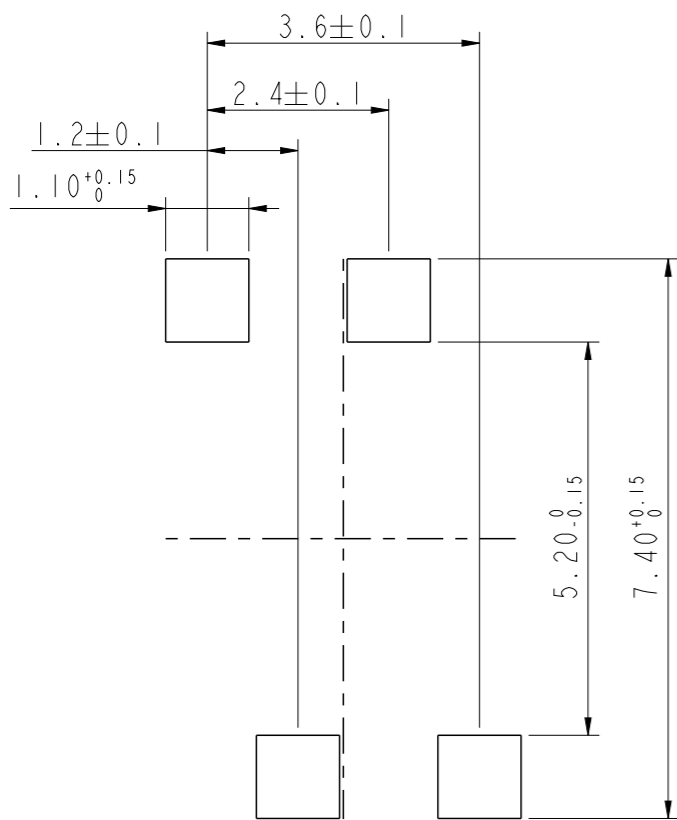
PRODUCT NUMBER	PACKAGING
10080212-001CLF	TAPE & REEL



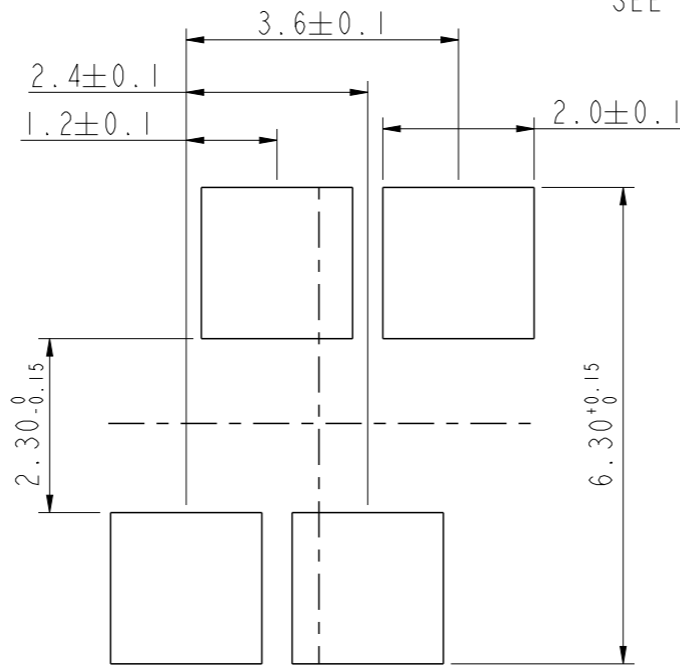
COVER ASSEMBLED STATUS

NOTES:

- HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL94 V-0, COLOR: BLACK
- CONTACT: COPPER ALLOY
 PLATING SPEC.: CONTACT POINT 0.127um MIN. Au AND SOLDER TAIL AREA 0.08um MIN. Au OVER 1.27um MIN. Ni UNDERPLATE OVERALL
- COVER: HIGH TEMPERATURE THERMOPLASTIC, UL94 V-0, COLOR: BLACK
- CONTACT GAP SPEC.: 4.2mm FROM BASE DATUM A AT 1.5mm OF CONTACT POINT HEIGHT
- NORMAL FORCE SPEC.: MIN. 0.39N AT 1.7mm OF CONTACT POINT HEIGHT
- SOLDER TAIL CO-PLANARITY: 0.10mm MAX.
- COVER RETENTION FORCE: 0.196N(20gf)~9.8N(1Kgf)
- PRODUCT SPEC.: GS-12-272
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOUR PHASE REFLOW OVEN
- NO CRACK AT -40°C ~ 265°C ALLOWED ON PLASTIC HOUSING AFTER PIN INSERTION
- REFER TO PAGE 2 FOR CORROSION TEST SEQUENCE
- ALL MATERIALS SHOULD BE COMPLY WITH SPM ENVIRONMENT-RELATED SUBSTANCES SPECIFICATION: 69707219***
- A SYMBOL $\triangle G$ WILL BE NEXT TO ANY DIMENSION, VIEW, OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION



RECOMMENDED SOLDER PAD LAYOUT




RECOMMENDED CONTACT PAD LAYOUT

spec ref	dr	Louis Ng	2010/07/05	projection	MM	size	A3	scale	10.000
tolerance std	eng	Dennis Goh	2014/02/24		← →	ecn no	ELX-S-16098-1	rel level	Released
ASME Y14.5	chr	-	-						
TOLERANCES UNLESS OTHERWISE SPECIFIED	appr	Chen-Hong Tan	2014/02/25	product family					
surface	linear	0.X	±0.25		title	4 PINS SPINDLE CONNECTOR	dwg no	10080212	rev
ASME Y14.5	angular	0.XX	±0.13						
		0.XXX	±0.050						
www.fci.com	cat. no.	Product - Customer Drw		sheet 1 of 2					



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CORROSION TEST SEQUENCE

(A) BEFORE QUALIFICATION: 3 WEEKS, 5EA PER WEEK. (TOTAL Q'TY: 15 EA) 

- 1) PARTS MUST SHOW NO SIGN OF CORROSION AFTER BEING EXPOSED TO 60°C ± 2°C AT 80% ± 3% RELATIVE HUMIDITY FOR BELOW PERIOD BY PURPOSE.
- 2) THE TEMPERATURE GRADIENT FROM 25°C TO 60°C SHALL BE 10°C PER HOUR TO PREVENT CONDENSATION.
- 3) THE SAMPLES AFTER ENVIRONMENT TEST NEED FURTHER CONDUCT BELOW TESTS FOLLOWING 3.4.1 AND 3.4.3 OF THE SEAGATE SPECIFICATION 649023111

3.1 APPEARANCE TEST (3.4.1 OF 649023111):

TEST SHALL USE A MICROSCOPE EXAMINATION WITH A 40X MAGNIFICATION MINIMUM. THE FINISHED PLATING SHALL BE CONTIGUOUS, SMOOTH, UNIFORM AND OF EVEN DENSITY AND COLOR. THERE SHALL BE NO CHEMICAL RESIDUE, BLISTERS, NODULES, PEELING, FLAKING, CRACKS, BREAKS, VOIDS, GAS STREAKS, ORANGE PEELING, OR CORROSION WHEN INSPECTED AT A DISTANCE OF 30 INCHES (ARM'S LENGTH) WITH NORMAL UNAIDED VISION AND ILLUMINATED WITH 100 FOOT-CANDLES MINIMUM. SLIGHT DISCOLORATION AND STAINING RESULTING FROM POST BAKING, HEAT TREATING, OR WATER EVAPORATION SHALL NOT BE CAUSE FOR REJECTION.

3.2 ADHESION TEST (3.4.3 OF 649023111)

THE ADHESION SHALL BE SUCH THAT THERE SHALL BE NO SEPARATION FROM THE BASIS METAL AT THE INTERFACE OF THE PLATING WHEN SUBJECTED TO TESTING AS SPECIFIED IN ASTM B 571 OR ASTM D 3359. TESTS SHALL USE A MICROSCOPE EXAMINATION WITH A 10X MAGNIFICATION MINIMUM. FIELD TESTS.

3.2.1 BEND TEST. THE TEST SPECIMENS SHALL BE BENT REPEATEDLY THROUGH AN ANGLE OF 180° ON A DIAMETER EQUAL TO THE THICKNESS OF THE SPECIMEN UNTIL FRACTURE OF THE BASE METAL OCCURS. FOLLOWING FRACTURE OF THE BASIS METAL, IT SHALL NOT BE POSSIBLE TO DETACH ANY APPRECIABLE AREAS OF THE COATING WITH A SHARP INSTRUMENT. THE ADHESION SHALL BE SUCH THAT WHEN EXAMINED AT A MAGNIFICATION OF 4 DIAMETERS, NEITHER THE GOLD NOR ANY ELECTRODEPOSITED UNDERCOAT SHALL SHOW SEPARATION FROM THE BASIS METAL AT THE INTERFACE (OR FROM EACH OTHER AT AN INTERFACE).

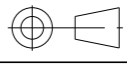


3.2.2 CUT TEST. THE ADHESION OF PLATED ARTICLES SHALL BE DETERMINED BY CUTTING THE PLATING FROM THE BASIS METAL AT THE INTERFACE(S) WITH A SHARP INSTRUMENT. THE SPECIMENS SHALL BE VISUALLY EXAMINED AT A MAGNIFICATION OF 4 DIAMETERS TO DETERMINE WHETHER REMOVAL HAS BEEN CAUSED BY CUTTING AWAY OF AN ADHERENT PLATE OR LIFTING OF A NON-ADHERENT PLATE.

3.2.3 BAKE TEST. ADHESION MAY BE DETERMINED BY HEATING THE PARTS IN AN OVEN AT 250°-300°F (121°-149°C) LONG ENOUGH TO BRING THE ITEMS TO TEMPERATURE AND THEN CONTINUED FOR 30 MINUTES. THE TEST SPECIMENS SHALL BE REMOVED, COOLED IN AIR AND EXAMINED AT A MAGNIFICATION OF 4 DIAMETERS FOR EVIDENCE OF FLAKING, PEELING, OR BLISTERING OF THE GOLD DEPOSIT. ANY FLAKING, PEELING, OR BLISTERING CONSTITUTES FAILURE OF THE SPECIMEN.

(B) AFTER QUALIFICATION: 4 DAYS (96 HOURS), TEST RESULT SHALL BE REPORTED TO CUSTOMER SQE EVERY SECOND WEEK.



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spec ref		dr	Louis Ng	2010/07/05	projection	MM	size	A3	scale	10.000
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED	eng	Dennis Goh	2014/02/24		← →	ecn no		ELX-S-16098-1	
ASME Y14.5		chr	-	-			rel level		Released	
surface 		linear	appr	Chen-Hong Tan	2014/02/25	product family		dwg no	10080212	rev
ASME Y14.5	angular	www.fci.com		cat. no.	Product - Customer Drw			sheet 2 of 2		
	0.X	±0.25			4 PINS SPINDLE CONNECTOR					
	0.XX	±0.13								
	0.XXX	±0.050								
	0°	±2°								